

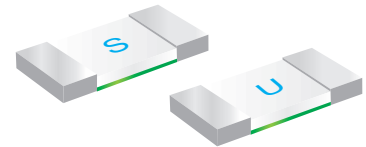
Fast Acting | 0.126x0.064 inch

1206HV Series

Thick Film Chip Fuses



1206HV Series are the fuses set the industry standard for performance, reliability and quality. The solder-free design provides excellent on-off and temperature cycling characteristics during use and also makes our SMD fuses more heat and shock tolerant than typical subminiature fuses.



Features

- AEC-Q200 Automotive Grade Certified
- Rapid interruption of excessive current
- Compatible with reflow and wave solder
- Excellent environmental integrity
- One time positive disconnect
- Lead Free and Halogen free material

Electrical Characteristics

Amp Rating	% of Amp Rating	Opening Time
250mA~20A	100%	4 Hours Min.
250mA~5A	250%	5 Seconds Max.
6A~20A	350%	5 Seconds Max.

Specifications

Part Number	Ampere Rating (A)	Voltage Rating	Interrupting Rating	Typical Cold Resistance (Ohms)	Typical Melting I ² t (A ² Sec)	Typical Voltage Drop (V)	Marking Code
1206HV-R250	0.250	125Vac @ 50A 125Vdc @ 50A		3.608	0.00012	1.407	.25
1206HV-R375	0.375			1.882	0.0003	0.718	E
1206HV-R500	0.500			1.028	0.0005	0.650	0.5
1206HV-R750	0.750			0.850	0.0012	1.0	.75
1206HV-1A	1.00			0.240	0.00075	0.300	H
1206HV-1.25A	1.25			0.175	0.009	0.290	
1206HV-1.5A	1.50			0.125	0.013	0.250	1.5
1206HV-2A	2.00			0.080	0.04	0.200	N
1206HV-2.5A	3.50			0.038	0.045	0.140	2.5
1206HV-3A	3.00			0.032	0.065	0.130	P
1206HV-3.5A	3.50	0.025	0.08	0.120	3.5		
1206HV-4A	4.00	72Vdc @ 50A		0.020	0.11	0.110	S
1206HV-5A	5.00			0.013	0.185	0.100	T
1206HV-6A	6.00			0.0155	8	0.140	F
1206HV-7A	7.00			0.0115	10	0.130	7
1206HV-8A	8.00	48Vdc @ 150A 32Vdc @ 150A		0.0076	12	0.123	V
1206HV-10A	10.00			0.0055	18	0.110	U
1206HV-12A	12.00			0.005	11.5	0.085	12
1206HV-15A	15.00			0.0034	16.5	0.078	15
1206HV-20A	20.00			0.0022	40	0.080	Q

- AC Interrupting Rating (measured at designated voltage, 100% power factor); DC Interrupting Rating (measured at designated voltage, time constant of less than 50 microseconds, battery source)
 - DC Cold Resistance are measured at <10% of rated current in ambient temperature of 25degrees
 - Typical Pre-arcing I²t are measured at 10In Current.
- Specifications are subject to change without notice. Application testing is strongly recommended.

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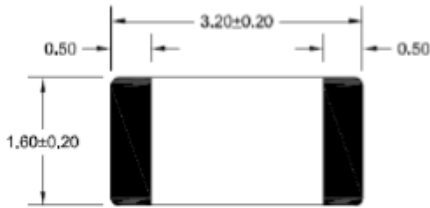
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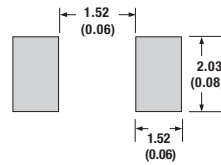
Dimension

Unit: mm/inch

Top view



Pad layout



Side view

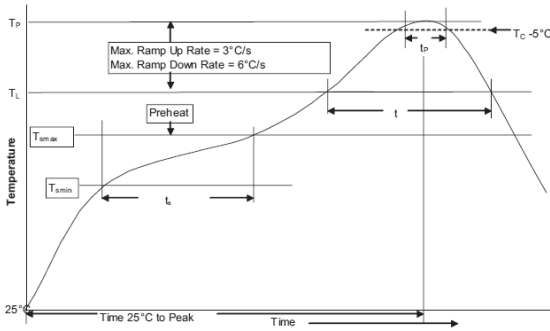


Packaging

- Quantity: 3,000pcs
- 8mm wide tape on 178mm(7 inch) diameter reel -specification EIA Standard 481.

Recommended stencil thickness is 0.15mm (6A-20A)

Soldering Parameters

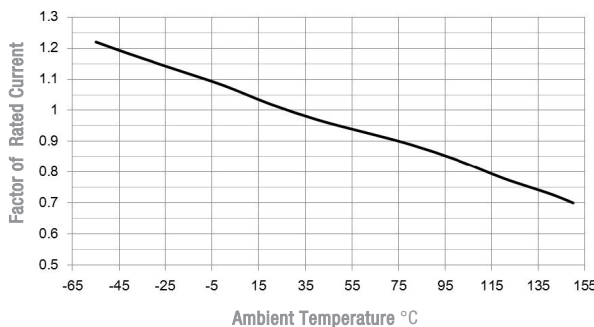


Wave Soldering: 260°C, 10 seconds max.
Infrared Reflow: 260°C, 30 seconds max.

IR Reflow Profile

Preheat Heat	
Temperature min (T _{sm})	150°C
Temperature max(T _{sm})	200°C
Time (T _{sm} to T _{sm}) (ts)	60 - 120 seconds
Average ramp-up rate (T_{sm} to T_p)	3°C/second max.
Liquidous temperature (T_L)	217°C
Time at liquidous (t _L)	60 - 150 seconds
Peak temperature(T_p)	260°C
Time within 5°C of actual peak Temperature (t_p)	30 seconds
Average ramp-down rate (T_p to T_{sm})	6°C/second max.
Time 25 °C to peak temperature	8 minutes max.

Temperature Derating Curve



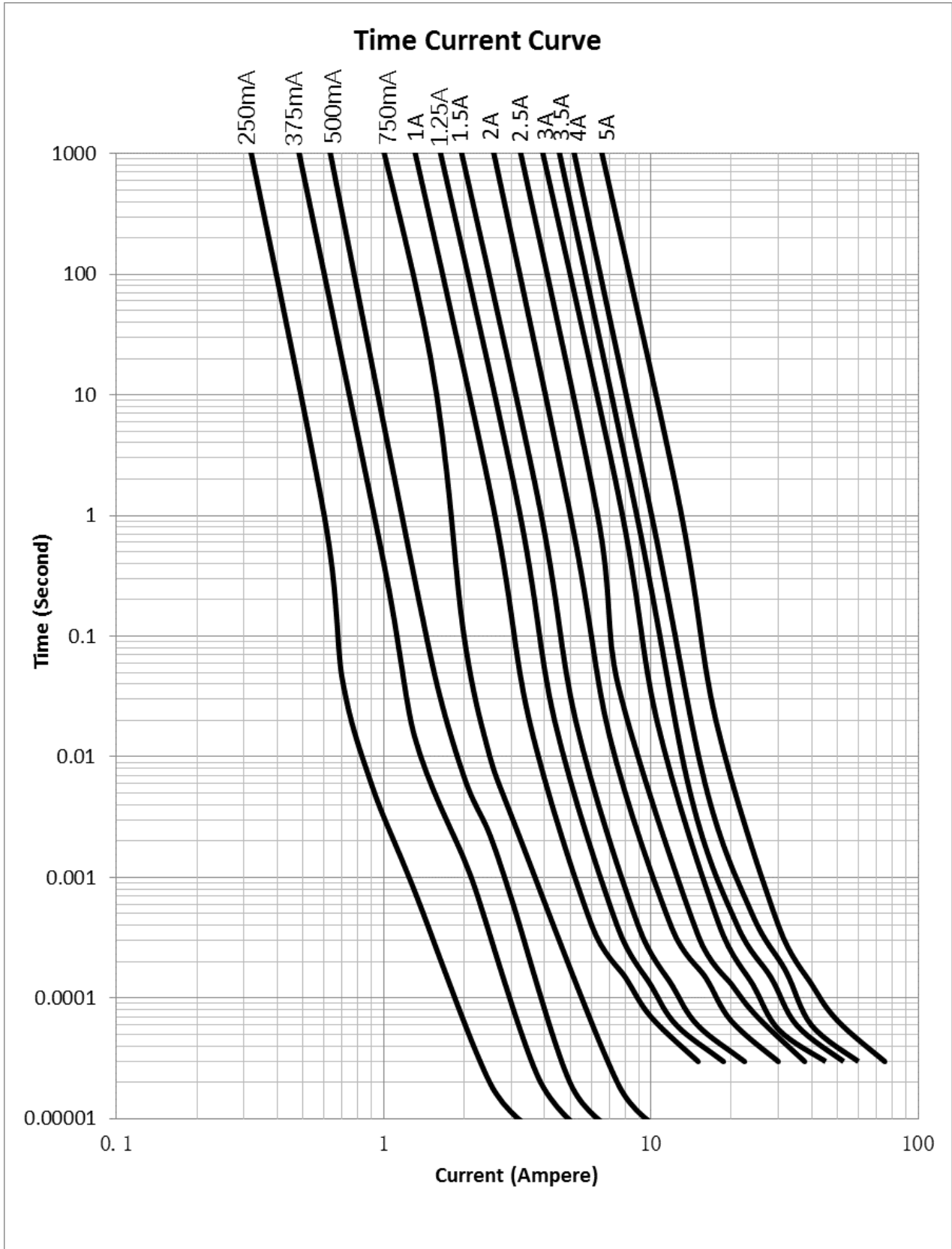
- Normal ambient temperature: 23+/-3 C
- Operating temperature: -55 ~ 150 C, with proper correction factor applied

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Average Time Current Curves



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